

INTEGRATED CIRCUITS, SILICON, MONOLITHIC, 35KLUT RADIATION-HARDENED FPGA (NG-MEDIUM)				<b>382A</b>												
Procurement Specifications	Manufacturer	Nature of Approval	Supervising Authority	Initial Qualification Date												
Generic ESCC <a href="#">9000</a> Detail ESCC <a href="#">9304/010</a>	<a href="#">NanoXplore, Sèvres, France</a>	Qualification	CNES	Aug 2022												
Remarks																
<p>Qualified range:</p> <table border="1"> <thead> <tr> <th>Detail spec</th> <th>Variant Number</th> <th>Based on Type</th> <th>Case</th> <th>Terminal Material and Finish</th> <th>Weight max g</th> </tr> </thead> <tbody> <tr> <td>9304/010</td> <td>01</td> <td>NX1H35AS</td> <td>CQFP-352</td> <td>D2</td> <td>28.6</td> </tr> </tbody> </table> <p>Based on STM C65SPACE ASIC platform technology. Qualified domain is listed in QML Technology Description in <a href="#">REP006</a>.</p> <p>Operating Temperature Range (°C): -55 to +125</p>					Detail spec	Variant Number	Based on Type	Case	Terminal Material and Finish	Weight max g	9304/010	01	NX1H35AS	CQFP-352	D2	28.6
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9304/010	01	NX1H35AS	CQFP-352	D2	28.6											

INTEGRATED CIRCUITS, SILICON, MONOLITHIC, 536KLUT RADIATION-HARDENED SoC FPGA (NG-ULTRA)				<b>395</b>
Procurement Specifications	Manufacturer	Nature of Approval	Supervising Authority	Initial Qualification Date
Generic ESCC <a href="#">9000</a> Detail ESCC <a href="#">9304/012</a>	NanoXplore, Sèvres, France	Qualification	CNES	Nov 2025
Remarks				
Qualified range:				
Detail spec	Variant Number	Based on Type	Case	Weight max g
9304/012	01	NX2H540ATSC-FF1760 (NG-ULTRA)	Fine pitch Flip-Chip Organic Ball Grid Array with 1760 balls (FF1760)	42
Based on STM ASIC 28nm FDSOI platform technology. Qualified domain is listed in QML Technology Description in <a href="#">REP006</a> .				
Operating Temperature Range (°C): -40 to +125				